

ABSTRACT

5 A bumped semiconductor component includes bumped
contacts, a semiconductor die having die contacts, and a
redistribution circuit having conductors for establishing
electrical communication between the die contacts and the
bumped contacts. The redistribution circuit also includes
10 test contacts in electrical communication with the die
contacts and with the bumped contacts. The test contacts
allow the die to be tested without electrical engagement of
the bumped contacts. The bumped semiconductor component can
be contained on a wafer, or can be a singulated component
15 such as a flip chip package. A test system includes the
bumped semiconductor component, and an interconnect having
contacts configured to electrically engage the test contacts
without interference from the bumped contacts. If the test
contacts are aligned with the die contacts, the same
20 interconnect can be used to test the bare die as well as the
bumped component. A test method includes the steps of:
providing the bumped component with test contacts; providing
the interconnect with interconnect contacts configured to
engage the test contacts without interference from the bumped
25 contacts; and then testing the component by applying test
signals through the interconnect contacts to the test
contacts.